

# G200 Epoxy Laminate and Prepreg

Isola's **G200** product is a fully proven laminate and prepreg system designed to meet today's high reliability printed circuit board requirements. Blending Bismaleimide/Triazine (BT) and epoxy resin provides G200 with enhanced thermal, mechanical and electrical performance over most epoxy materials. G200 possesses performance characteristics that make it an excellent selection for large panel size, high layer count Printed Wiring Boards (PWB).

### www.isola-group.com/products/G200

#### **ORDERING INFORMATION:**

Contact your local sales representative or visit www.isola-group.com for further information.

#### **Isola Group** 3100 West Ray Road

Suite 301 Chandler, AZ 85226 Phone: 480-893-6527 Fax: 480-893-1409 info@isola-group.com Isola Asia Pacific (Hong Kong) Ltd. Unit 3512 - 3522, 35/F No. 1 Hung To Road, Kwun Tong, Kowloon, Hong Kong Phone: 852-2418-1318 Fax: 852-2418-1533 info.hkg@isola-group.com Isola GmbH Isola Strasse 2 D-52348 Düren, Germany Phone: 49-2421-8080 Fax: 49-2421-808164 info-dur@isola-group.com

### **High Performance**

G200 Data Sheet

Tg 180, Td 325 Dk 3.70, Df 0.013 /30

#### **Features**

- High Thermal Performance
  - ▶ Tg: 180°C (DSC)
  - Superior performance through multiple thermal excursions
  - Superior chemical and thermal resistance
- T260: 60 minutes
- T288: >10 minutes
- RoHS Compliant
- Low CTE from Ambient to 288°C
- Excellent Electrical Insulation in High Humidity and High Temperatures (CAF Resistance)
- Core Material Standard Availability
  - Thickness: 0.002" (0.05 mm) to 0.125" (3.2 mm)
  - Available in full size sheet or panel form
- Prepreg Standard Availability
  - Roll or panel form
  - Tooling of prepreg panels available
- Copper Foil Type Availability
- Standard HTE Grade 3
  - RTF (Reverse Treat Foil)
- ► VLP-2 (2 micron)
- Copper Weights
  - ½, 1 and 2 oz (18, 38 and 70 μm) available
  - Heavier copper available upon request
  - Thinner copper foil available upon request
- Glass Fabric Availability
- Standard E-glass
- Square weave glass fabric available
- Industry Approvals
  - ▶ IPC-4101C /30
  - ▶ UL File Number E41625

# **G200 Specifications**

		Typical Values			
r I	Property			Units Test Method	
		Typical Value	Specification	Metric (English)	IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC		180	150-200	°C	2.4.25
Decomposition Temperature (Td) by TGA @ 5% weight loss		325	-	<b>℃</b>	ASTM D3850
T260		60	-	Minutes	ASTM D3850
T288		>10	-	Minutes	ASTM D3850
CTE, Z-axis	A. Pre-Tg B. Post-Tg	55 275	AABUS -	ppm/ºC	2.4.24
CTE, X-, Y-axes	A. Pre-Tg B. Post-Tg	13/14 14/17	AABUS -	ppm/ºC	2.4.24
Z-axis Expansion (50-260°C)		3.30	-	%	2.4.24
Thermal Conductivity		0.35	-	W/mK	ASTM D5930
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched B. Etched	Pass	Pass Visual	Rating	2.4.13.1
Dk, Permittivity (Laminate & prepreg as laminated) Tested at 50% resin	A. @ 100 MHz (HP4285A) B. @ 1 GHz (HP4291A) C. @ 2 GHz (Bereskin Stripline) D. @ 5 GHz (Bereskin Stripline) E. @ 10 GHz (Bereskin Stripline)	3.80 3.70 3.70 3.65 3.65	5.4  	_	2.5.5.3 2.5.5.9 2.5.5.5 2.5.5.5 2.5.5.5
Df, Loss Tangent (Laminate & prepreg as laminated) Tested at 50% resin	A. @ 100 MHz (HP4285A) B. @ 1 GHz (HP4291A) C. @ 2 GHz (Bereskin Stripline) D. @ 5 GHz (Bereskin Stripline) E. @ 10 GHz (Bereskin Stripline)	0.0150 0.0150 0.0130 0.0150 0.0150	0.035  - - -	_	2.5.5.3 2.5.5.9 2.5.5.5 2.5.5.5 2.5.5.5 2.5.5.5
Volume Resistivity	A. 96/35/90 B. After moisture resistance C. At elevated temperature	- 8.9x10 <sup>8</sup> 6.5x10 <sup>8</sup>	1.0x10 <sup>6</sup> - 1.0x10 <sup>3</sup>	MΩ-cm	2.5.17.1
Surface Resistivity	A. 96/35/90 B. After moisture resistance C. At elevated temperature	- 2.21x10 <sup>6</sup> 4.4x10 <sup>8</sup>	1.0x10 <sup>4</sup> - 1.0x10 <sup>3</sup>	MΩ	2.5.17.1
Dielectric Breakdown		>60	_	kV	2.5.6
Arc Resistance		130	60	Seconds	2.5.1
Electric Strength (Laminate & prepreg as laminated)		45 (1175)	30 (750)	kV/mm (V/mil)	2.5.6.2
Comparative Tracking Index (CTI)		3 (175-249)	-	Class (Volts)	UL-746A ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile – all copper weights >17 microns B. Standard profile copper 1. After thermal stress 2. At 125°C (257°F) 3. After process solutions	1.14 (6.5) 	0.70 (4.0) 	N/mm (lb/inch)	2.4.8 2.4.8.2 2.4.8.3 - -
Flexural Strength	A. Lengthwise direction B. Crosswise direction	86,900 73,600	-	lb/inch <sup>2</sup>	2.4.4
Tensile Strength	A. Lengthwise direction B. Crosswise direction	51,551 42,436	-	lb/inch <sup>2</sup>	-
Young's Modulus	A. Grain direction B. Fill direction	3489 3199	-	ksi	WW
Poisson's Ratio	A. Grain direction B. Fill direction	0.182 0.160	-	-	XX
Moisture Absorption		0.2	-	%	2.6.2.1
Flammability (Laminate & prepreg as laminated)		V-0	_	Rating	UL 94
Max Operating Temperature		140	UL Cert	<b>℃</b>	_

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.

## www.isola-group.com/products/G200



The Isola name and Iogo are registered trademarks of Isola Corp. USA in the USA and other countries. All other trademarks mentioned herein are property of their respective owners. © 2012, Isola Group, All rights reserved.